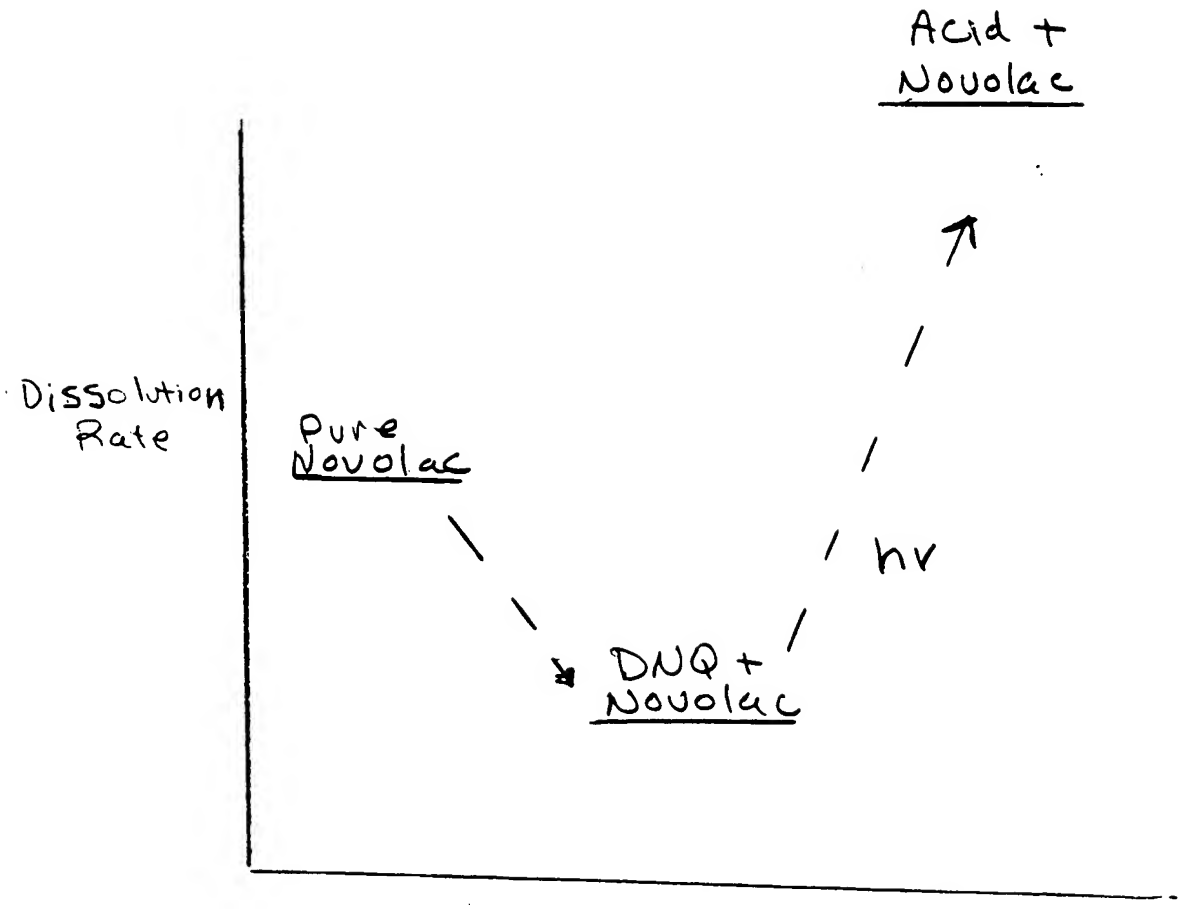


Fig. 1
(Prior Art)

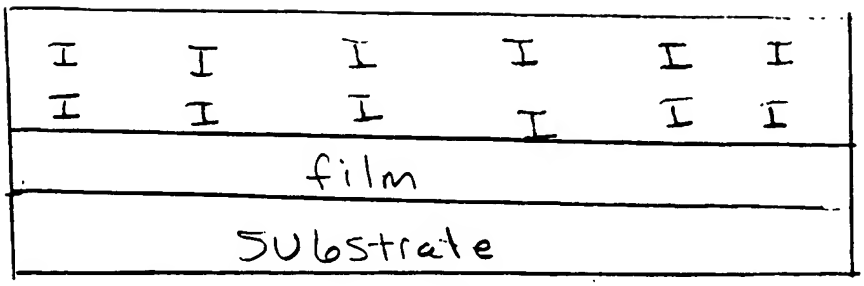


Fig. 2A
(Prior Art)

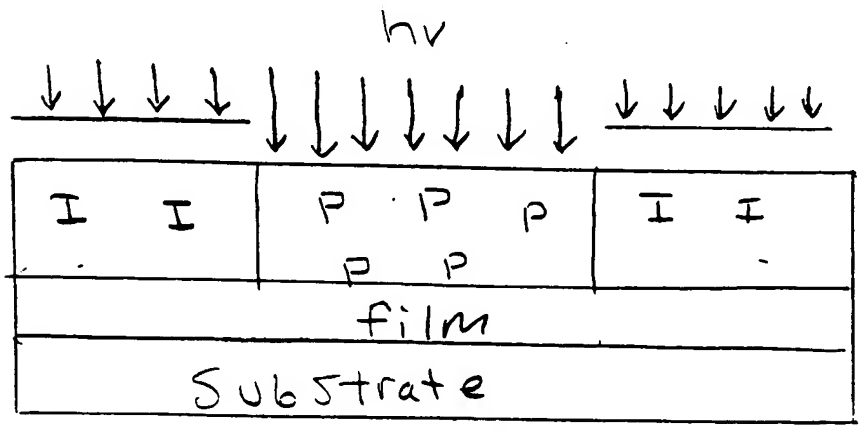


Fig. 2B
(Prior Art)

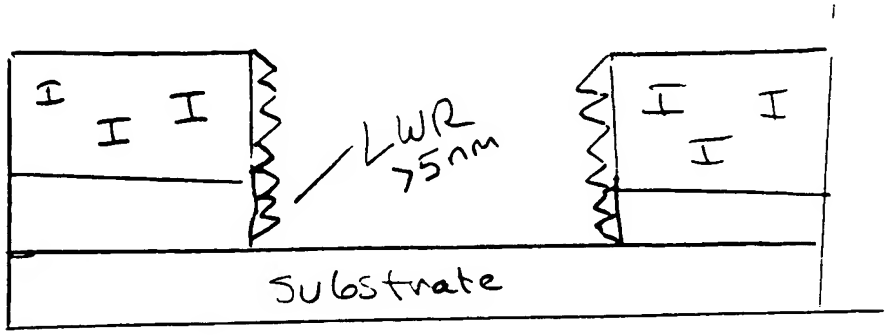


Fig 2C
(Prior Art)

300

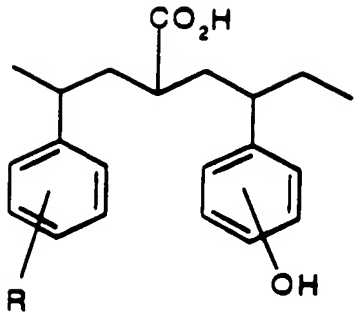
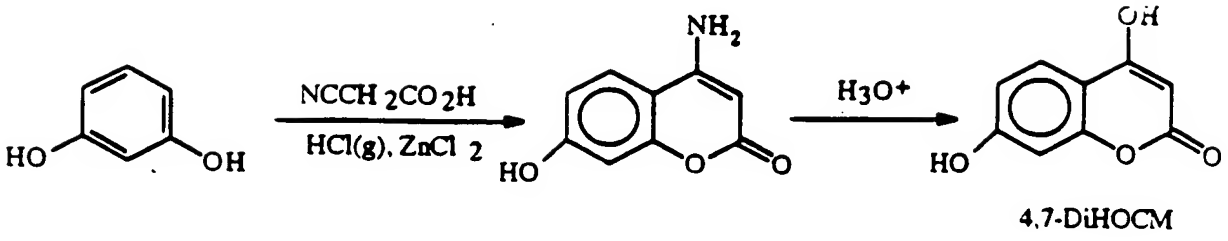
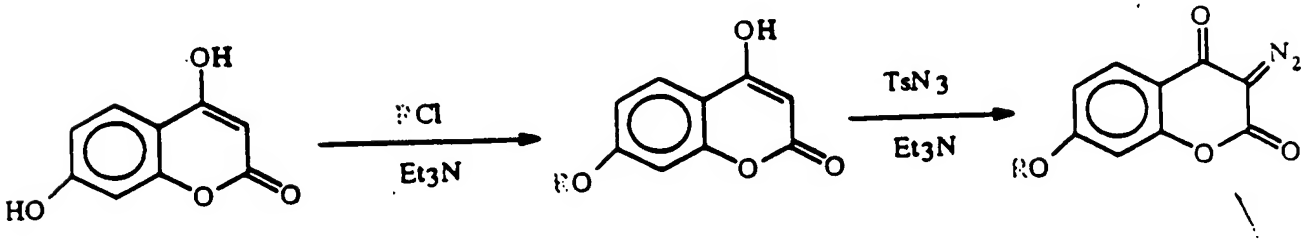


Fig. 3

400



4,7-DiHOCM



410

R = Ts-, t-BuCO-, MeCO-, MeOCO-, MeSO2-

Fig. 4

500

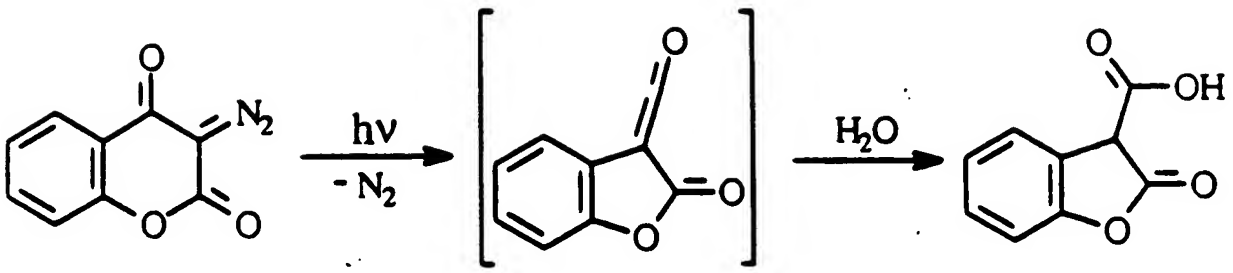


Fig. 5

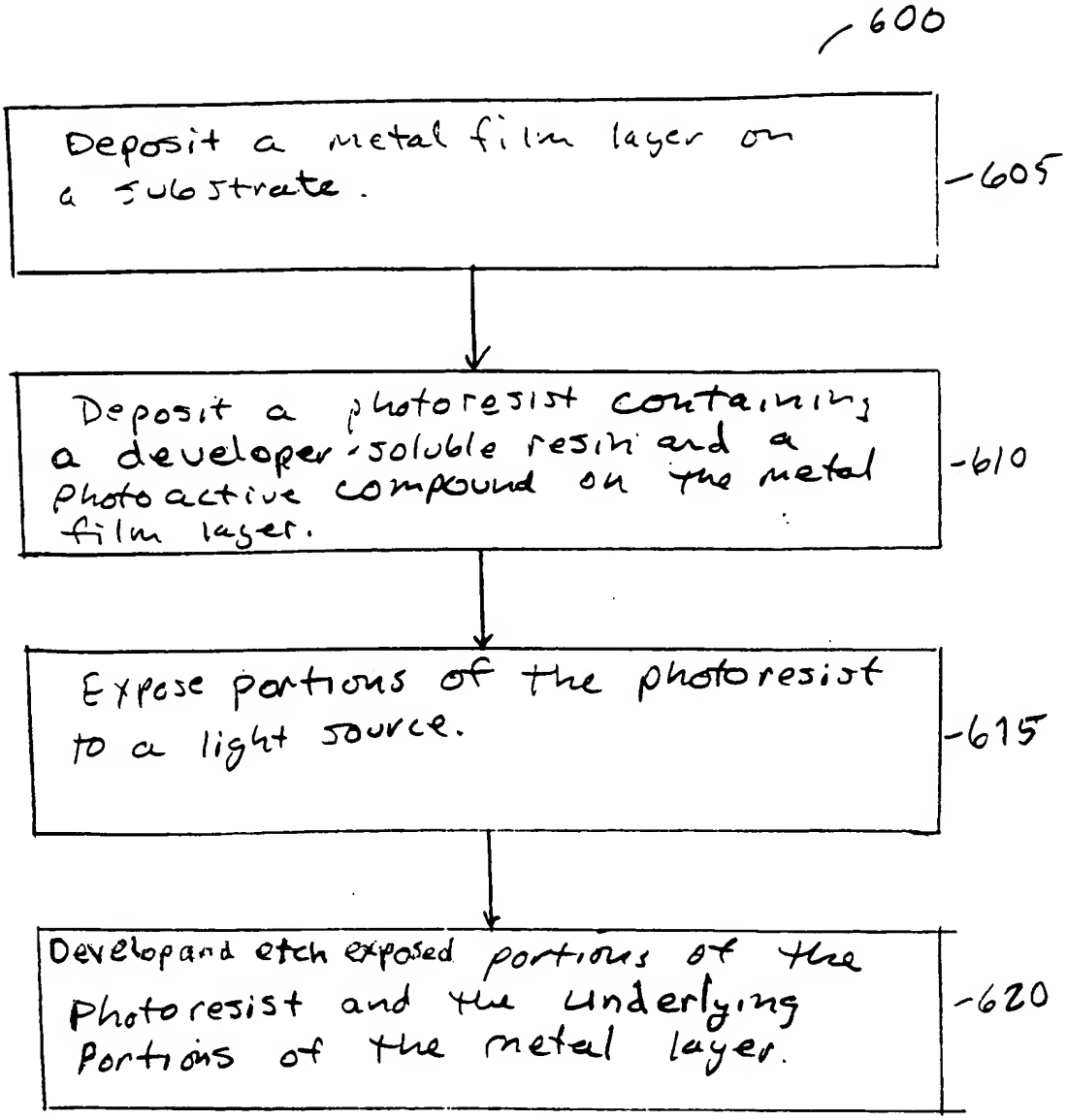

600
Deposit a metal film layer on a substrate.
605
Deposit a photoresist containing a developer-soluble resin and a photoactive compound on the metal film layer.
610
Expose portions of the photoresist to a light source.
615
Develop and etch exposed portions of the Photoresist and the underlying Portions of the metal layer.
620

Fig. 6